

# Erfahrungen mit RoHS-konformen Löten

- RoHS: **R**eduction **o**f **H**azardous **S**ubstances
- EU-Richtlinie: Muß bis Juli 2005 in allen Consumer-Produkten umgesetzt werden
- Vapor-Phase Reflow Oven (Kondensationslötofen) ist auf 230°C umgestellt
- Die meisten Bauteile lassen sich wie gewohnt löten
- Ein MCM (Multi-Chip-Module) von Axis macht Probleme ....
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ETRAX 100LX MCM 4+10  
22545 E2  
+0452  
TAIWAN

J5 INOUT2

JCPLD1

UCP1

K1

R15

JETH1

JSUBD1

N

ATMEL1

ICOM1

HADS UPD

R15

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R20

C9 R1

HADS UPON

R15

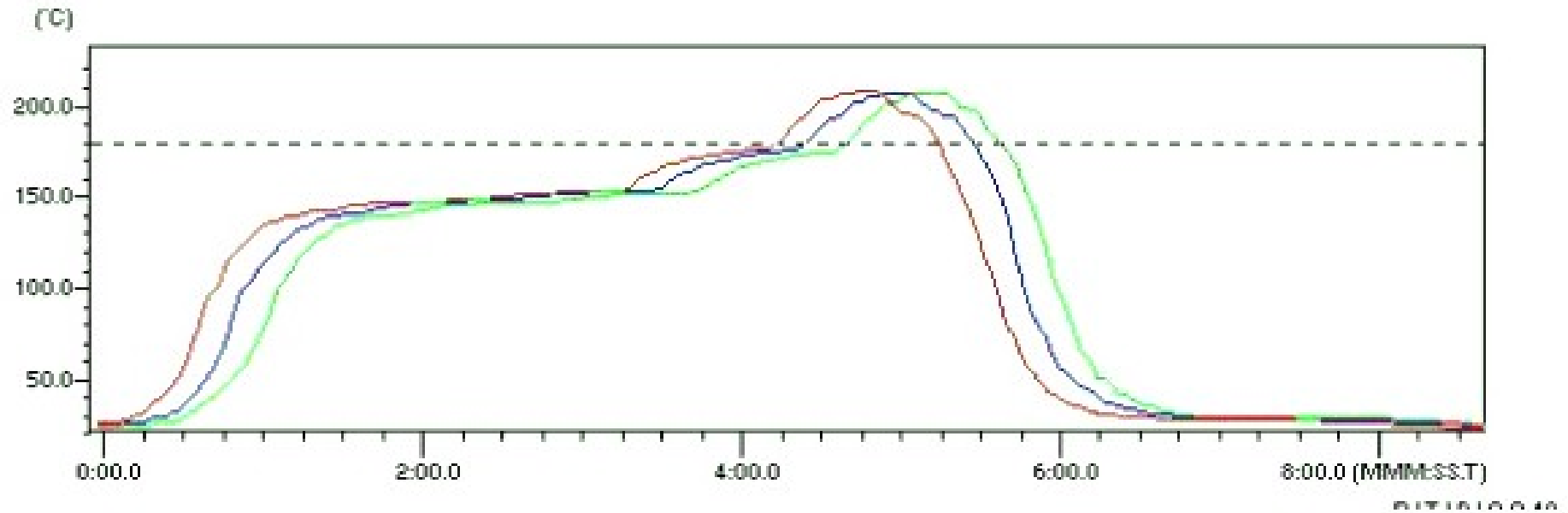
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## Recommended Reflow Profile for 63Sn/37Pb or 62Sn/36Pb/2Ag Solder Paste



*This profile is designed for use with Sn63 or Sn62 and can serve as a general guideline in establishing a reflow profile.*

### **Reflow Profile:**

- Heating-up @1~3°C/sec to 140°C
- Preheat @ 140-150°C for 120 ~ 160 sec
- Ramp @ 2~3 °C/sec to peak temperature (220 ~ 225 °C),  
Temperature over 183°C for 45~ 75 sec
- Cooling down to room temperature @4~2°C/sec to avoid undesired intermetallic compound layer.